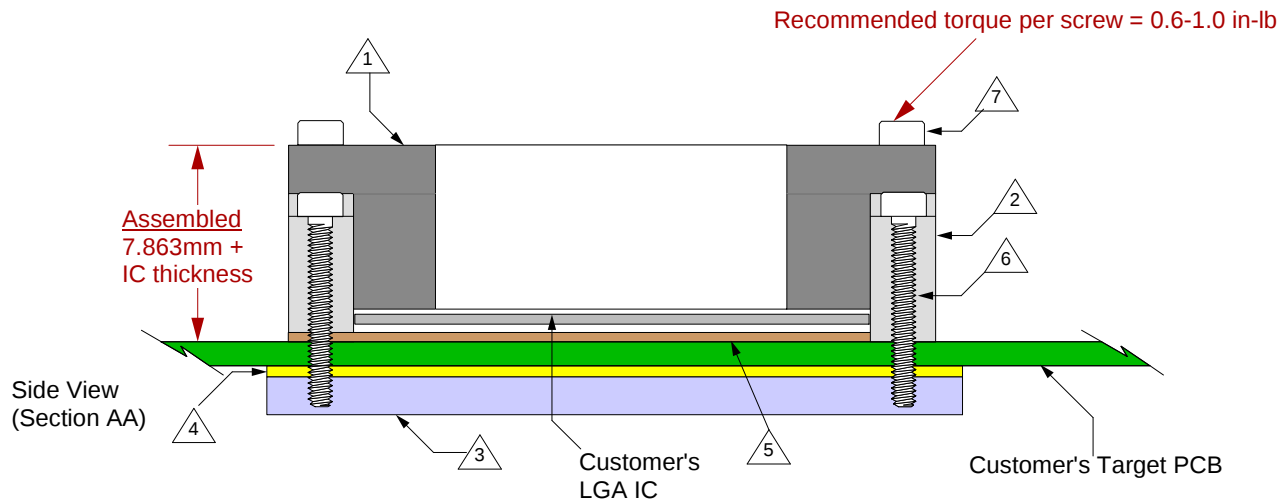
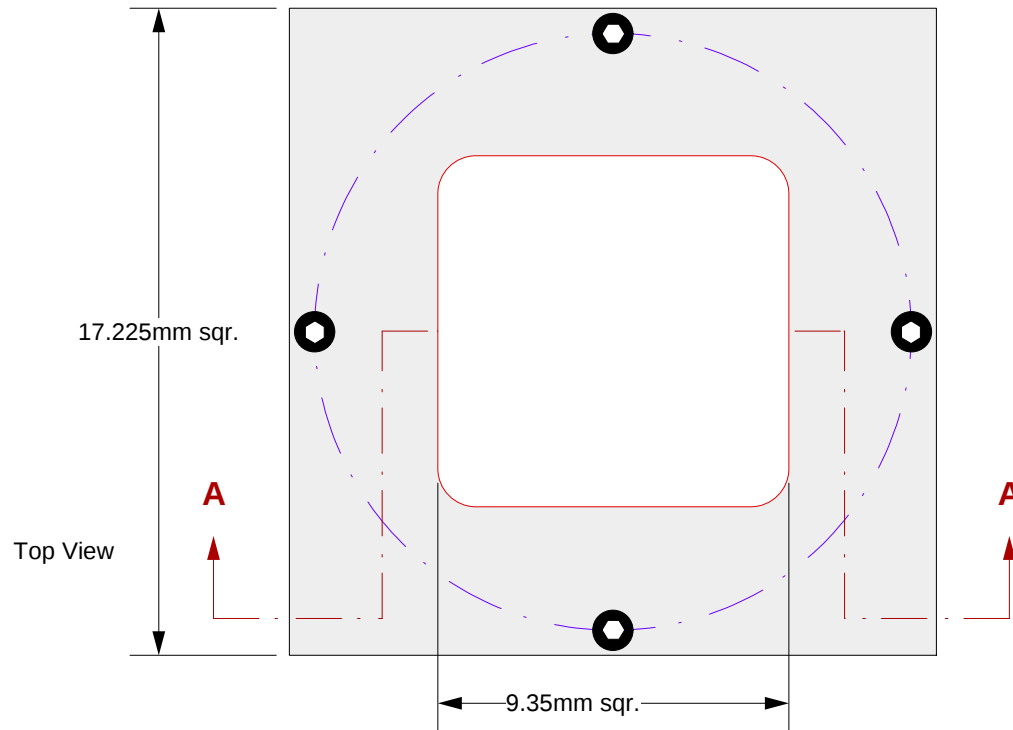


40 GHz LGA Socket - Direct mount, solderless

Features

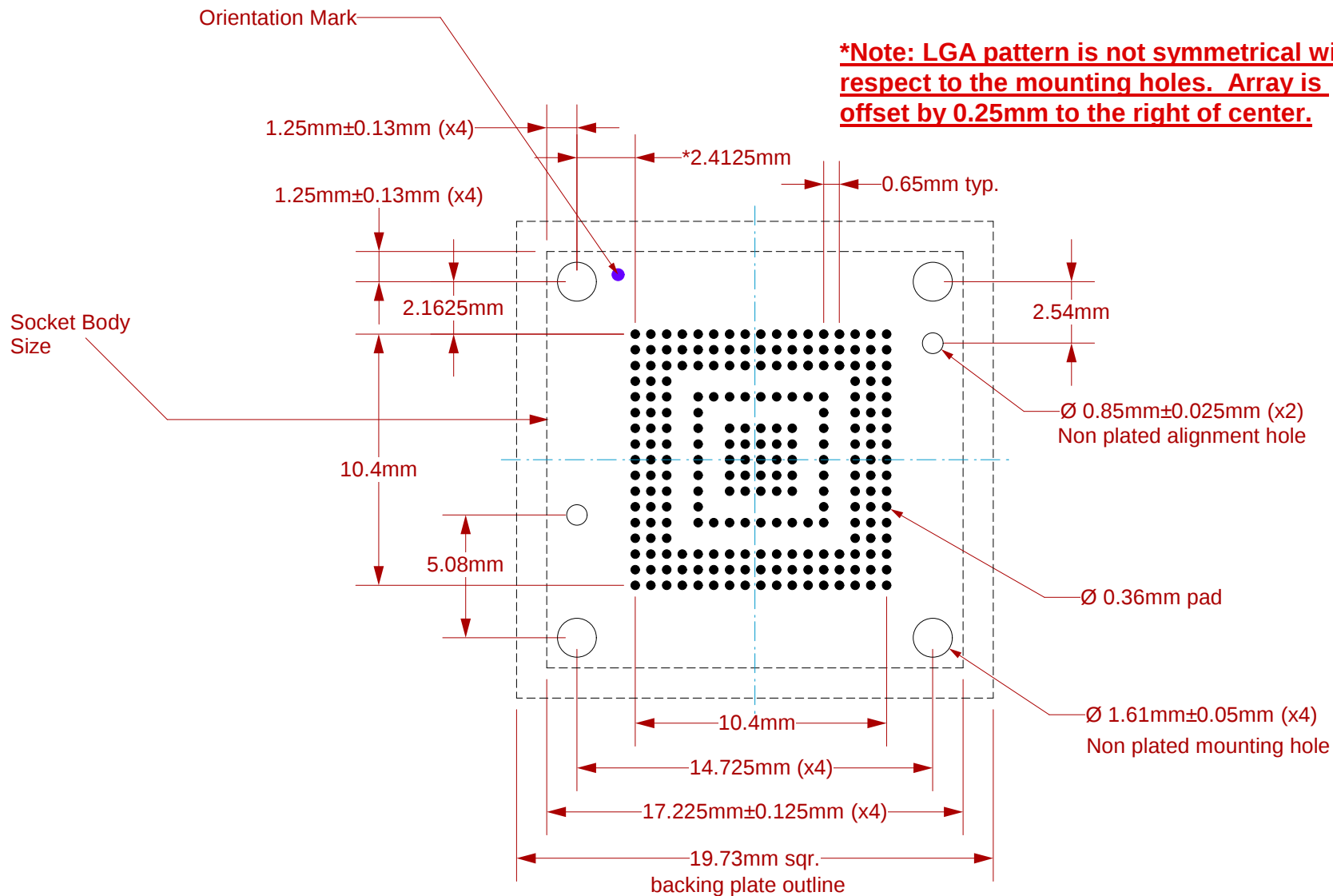
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid



- 1 Socket Lid: Black anodized Aluminum with compression plate; Thickness = 2.5mm, ~5mm projection for compression
- 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- 3 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.
- 4 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- 5 Interposer: Copper plated kapton and conductive elastomer; Thickness = 0.363mm.
- 6 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- 7 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.

XG-LGA-7001 Drawing		Status: Released	Scale: -	Rev: B
 © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 02/12/08	
	File: XG-LGA-7001 Dwg		Modified: 8/3/09, AE	

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.



Target PCB Recommendations

Total thickness: 1.6mm min.

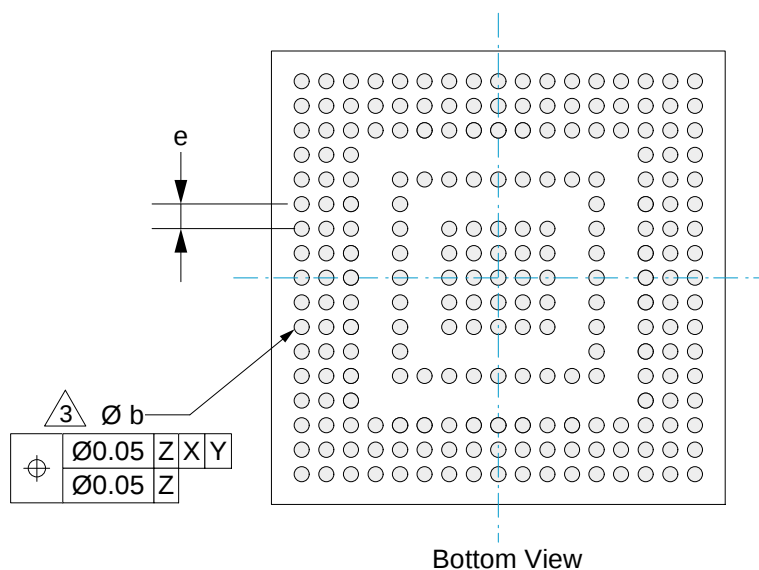
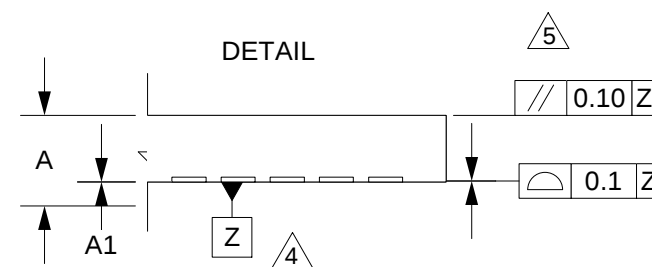
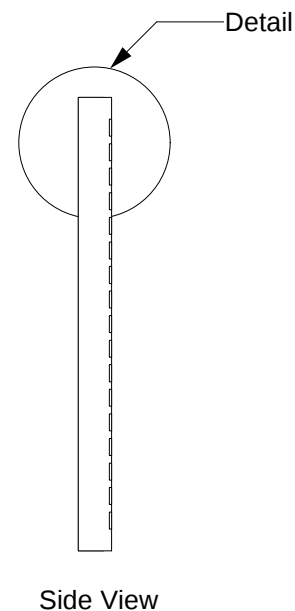
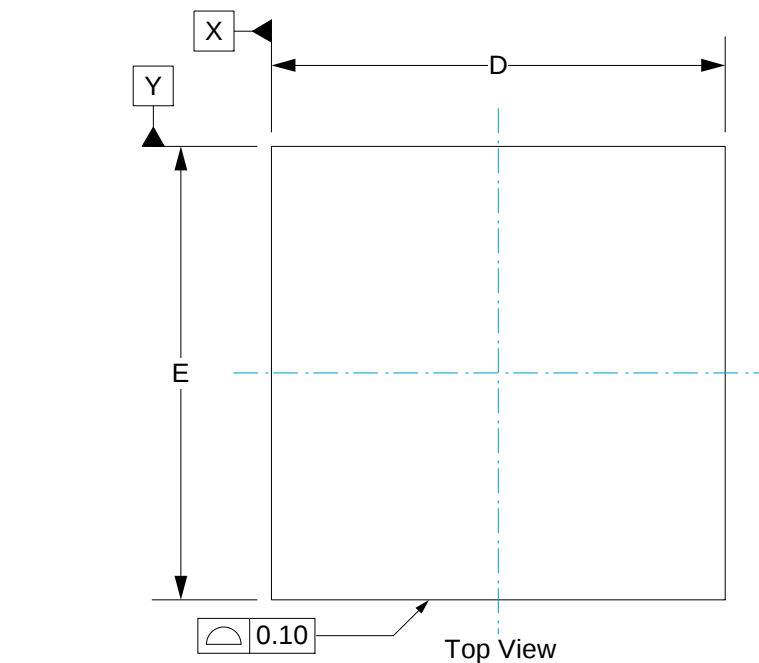
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

XG-LGA-7001 Drawing		Status: Released	Scale: 4:1	Rev: B
 © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 02/12/08	
	File: XG-LGA-7001 Dwg		Modified: 8/3/09, AE	



1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

3. Dimension b is measured at the maximum pad diameter, parallel to datum plane Z.

4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

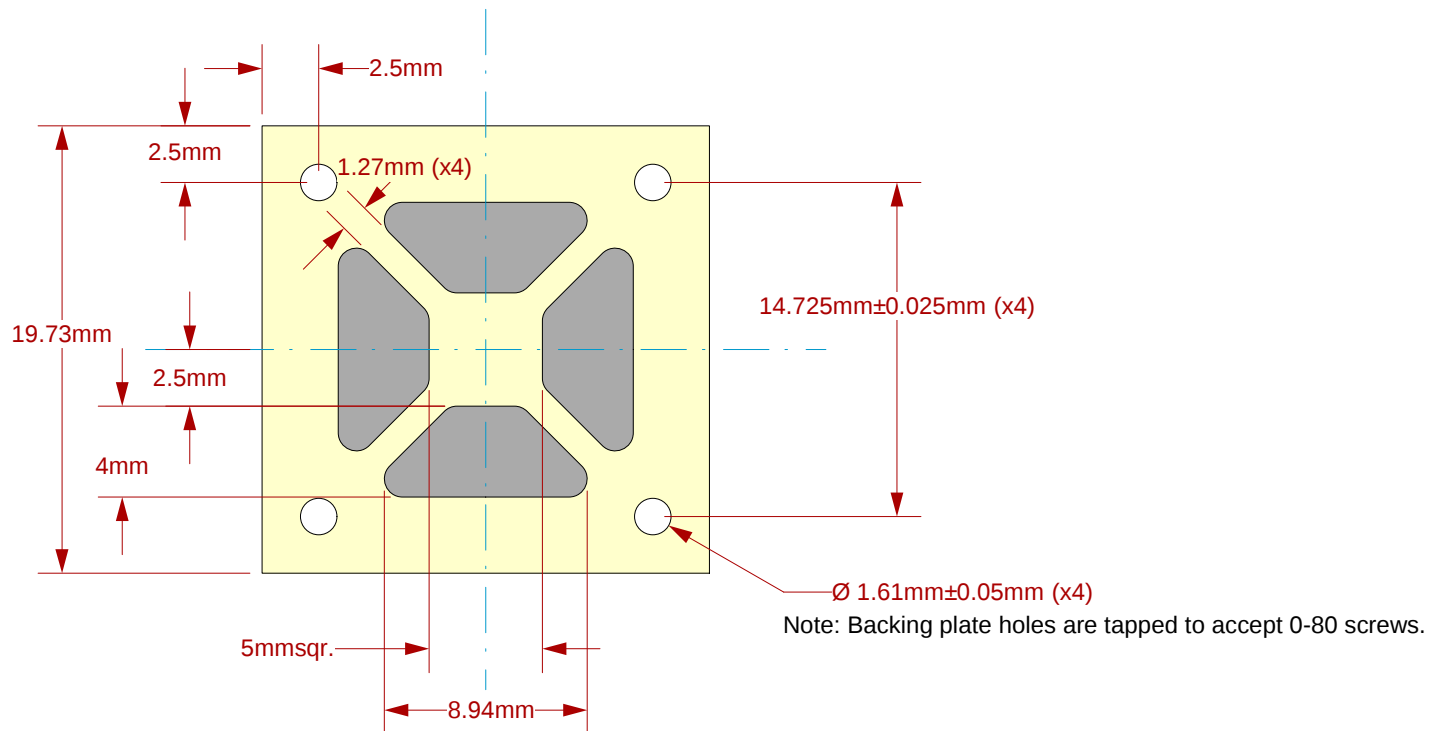
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		0.66
A1	0.0	0
b	0.30	
D	12.0 BSC	
E	12.0 BSC	
e	0.65 BSC	

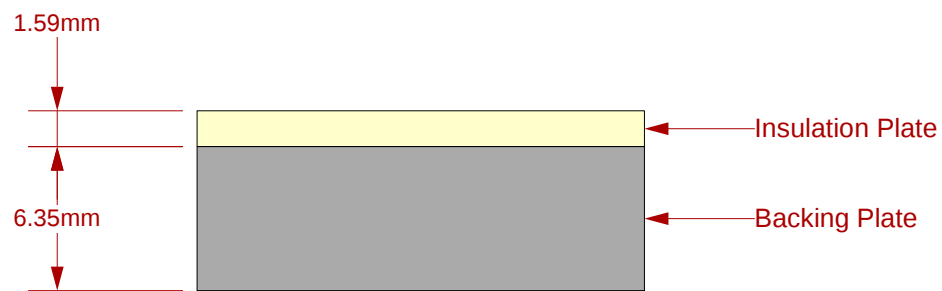
17 x 17 array

XG-LGA-7001 Drawing		Status: Released	Scale: 5:1	Rev: B
 © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 02/12/08	
	File: XG-LGA-7001 Dwg		Modified: 8/3/09, AE	

Top View



Side View



Description: Insulation Plate and Backing Plate

XG-LGA-7001 Drawing		Status: Released	Scale: 3:1	Rev: B
 © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: J. Glab		Date: 02/12/08	
	File: XG-LGA-7001 Dwg		Modified: 8/3/09, AE	

All dimensions are in mm.
All tolerances are $\pm 0.125\text{mm}$.
(Unless stated otherwise)